



BL-M8189FS6

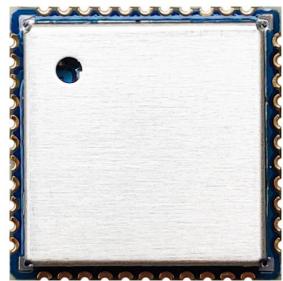
802.11n 150Mbps WLAN

SDIO Module Specification

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(Top view)



(Bottom view)

Module Name: BL-M8189FS6

Module Type: 802.11b/g/n 150Mbps 1T1R WLAN SDIO Module

Revision: V1.4

Customer Approval:

Company:

Title:

Signature:

Date:

LB-link Approval:

Title:

Signature:

Date:

Revision History

Revision	Summary	Release Date	Revised By
1.0	Official release	2020-03-25	
1.1	Optimized for ESD instructions	2020-04-25	
1.2	Update version (Specification checklist)	2023-03-03	
1.3	Update product picture	2023-09-04	Fnz
1.4	Update product picture and key components and module dimension tolerance	2025-01-13	Wbd

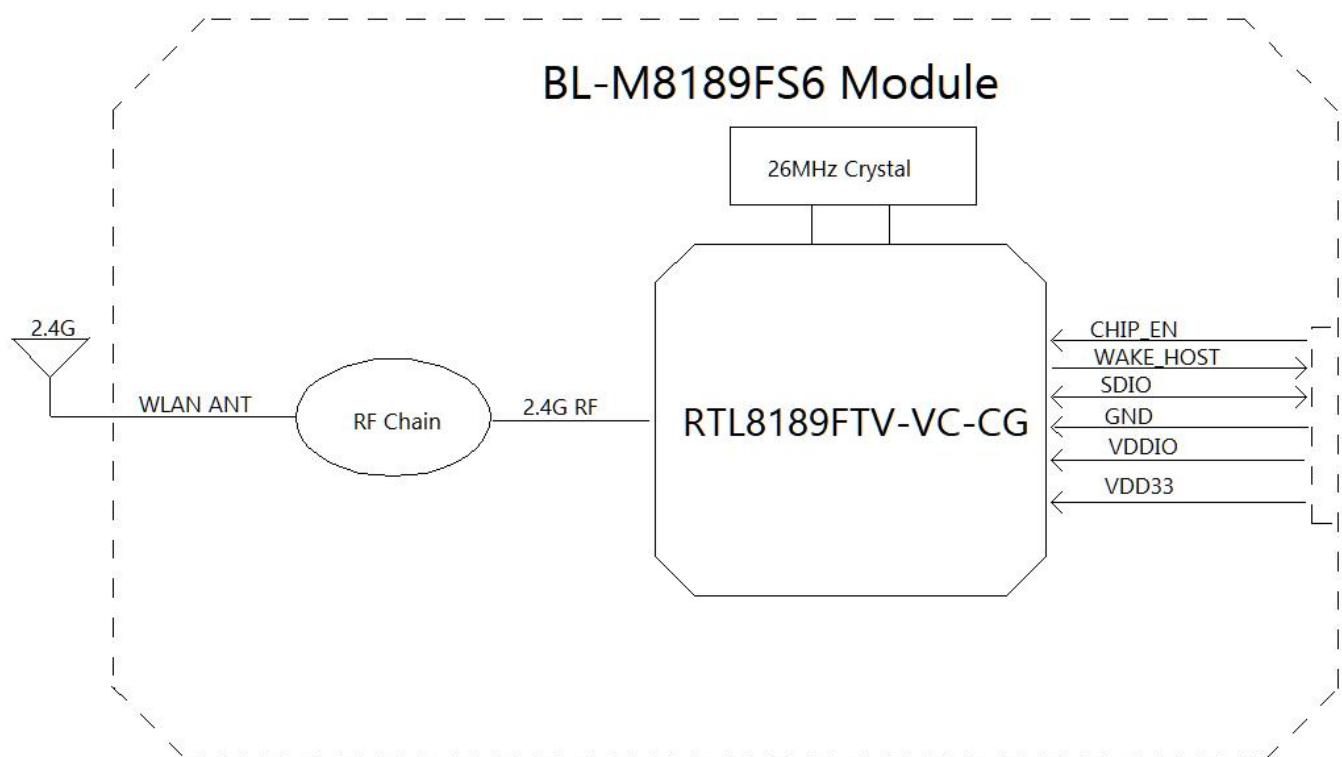
1. Introduction

BL-M8189FS6 is a highly integrated WLAN module, it contains a WLAN MAC, a 1T1R capable WLAN base band. It supports IEEE 802.11b/g/n standard and provides the highest PHY rate up to 150Mbps, offering feature-rich wireless connectivity and reliable throughput from an extended distance.

1.1 Features

- Operating Frequencies: 2.4~2.484GHz
- Host Interface is SDIO 2.0
- IEEE Standards: IEEE 802.11b/g/n
- Wireless PHY rate can reach up to 150Mbps
- Connect to external antenna through half hole pad
- DC $3.3V \pm 0.2V$ Main Power Supply and DC $3.3V \pm 0.2V/1.8V \pm 0.1V$ I/O Power Supply

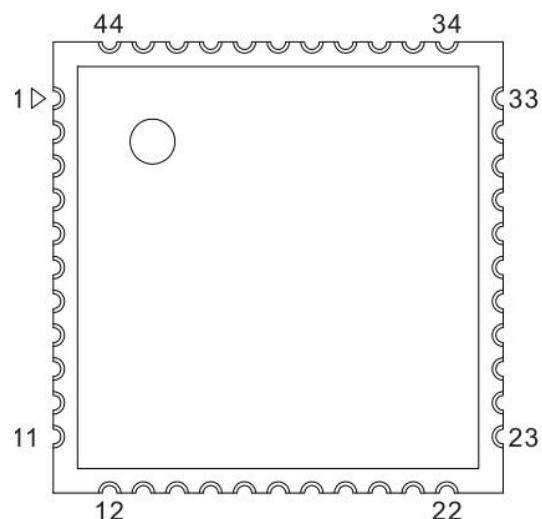
1.2 Block Diagram



1.3 General Specifications

Module Name	BL-M8189FS6
Chipset	RTL8189FTV-VC-CG
WLAN Standards	IEEE802.11b/g/n
Host Interface	SDIO 2.0
Antenna	Connect to the external antenna through half hole pad
Dimension	12*12*1.8mm (L*W*H)
Power Supply	DC 3.3±0.2V (main power) @ 400 mA (Max) DC 3.3±0.2V or 1.8±0.1V (SDIO and Digital I/O power)
Operation Temperature	-20°C to +70°C
Operation Humidity	10% to 95% RH (Non-Condensing)

2. Pin Assignments



(Top view)

2.1 Pin Definition

No.	Pin Name	Type	I/O Level	Module Pin Description
1	GND	RF		RF Ground
2	WLAN ANT	RF		RF pad for WLAN ANT

3	GND	RF		RF Ground
4	NC	/		NC
5	NC	/		NC
6	NC	/		NC
7	NC	/		NC
8	NC	/		NC
9	VDD33	P		DC3.3V Main power supply
10	NC	/		NC
11	NC	/		NC
12	CHIP_EN	I	VDD33	This pin can Externally Shutdown the module when it pulled low. Internal pull high by 100K resistor
13	WAKE HOST	O	VDDIO	Sheared with GPIO0. WLAN to wake-up HOST output
14	SD_D2	I/O	VDDIO	SDIO data line 2
15	SD_D3	I/O	VDDIO	SDIO data line 3
16	SD_CMD	I/O	VDDIO	SDIO command input
17	SD_CLK	I	VDDIO	SDIO clock input
18	SD_D0	I/O	VDDIO	SDIO data line 0
19	SD_D1	I/O	VDDIO	SDIO data line1
20	GND	P		Ground
21	NC	/		NC
22	VDDIO	P		Power supply for SDIO and other digital I/O. Based on customer application platform, it can choose 3.3V or 1.8V power input
23	NC	/		NC
24	NC	/		NC
25	NC	/		NC
26	NC	/		NC
27	NC	/		NC
28	NC	/		NC
29	NC	/		NC
30	NC	/		NC
31	GND	P		Ground

32	NC	/		NC
33	GND	P		Ground
34	NC	/		NC
35	NC	/		NC
36	GND	P		Ground
37	NC	/		NC
38	NC	/		NC
39	NC	/		NC
40	NC	/		NC
41	NC	/		NC
42	NC	/		NC
43	NC	/		NC
44	NC	/		NC

P: Power, I: Input, O: Output, I/O: In/Output, RF: Analog RF Port

3. Electrical and Thermal Specifications

3.1 Recommended Operating Conditions

Parameters		Min	Typ	Max	Units
Ambient Operating Temperature		-20	25	70	°C
External Antenna VSWR			1.7	2.1	/
Supply Voltage	VDD33	3.1	3.3	3.5	V
	VDDIO	1.7	1.8	1.9	V
		3.1	3.3	3.5	V

3.2 Digital 3.3V GPIO DC Specifications

Symbol	Parameter	Min	Typ	Max	Units
VIH	Input High Voltage	2.0	3.3	3.5	V
VIL	Input Low Voltage		0	0.9	V

VOH	Output High Voltage	2.97	--	3.3	V
VOL	Output Low Voltage	0	--	0.33	V

3.3Digital 1.8V GPIO DC Specifications

Symbol	Parameter	Min	Typ	Max	Units
VIH	Input High Voltage	1.7	1.8	1.9	V
VIL	Input Low Voltage	--	0	0.8	V
VOH	Output High Voltage	1.62	--	1.8	V
VOL	Output Low Voltage	0	--	0.18	V

3.4 Current Consumption

Conditions : VDD33=3.3V ; Ta:25°C			
Use Case	VDD33 Current (average)		
	Typ	Max	Units
WLAN Unassociated (Linux Driver)	40	60	mA
2.4G 11b@1Mbps TX@17dBm (1RF test)	273	320	mA
2.4G 11b@1Mbps RX(1RF test)	60	70	mA
2.4G 11b@11Mbps TX@17dBm (1RF test)	280	320	mA
2.4G 11b@11Mbps RX(1RF test)	55	70	mA
2.4G 11g@6Mbps TX@17dBm (1RF test)	265	285	mA
2.4G 11g@6Mbps RX (1RF test)	60	70	mA
2.4G 11g@54Mbps TX@14dBm (1RF test)	260	270	mA
2.4G 11g@54Mbps RX (1RF test)	60	65	mA
2.4G 11n@HT20_MCS0 TX@16dBm (1RF test)	275	287	mA
2.4G 11n@HT20_MCS0 RX (1RF-Test)	60	70	mA
2.4G 11n@HT20_MCS7TX@14dBm (1RF test)	265	282	mA
2.4G 11n@HT20_MCS7 RX (1RF-Test)	59	70	mA

2.4G 11n@HT40_MCS7 TX@14dBm (1RF test)	275	291	mA
2.4G 11n@HT40_MCS7 RX (1RF-Test)	60	80	mA

4. 2.4G WLAN RF Specifications

Conditions : VDD33=3.3V ; Ta:25°C	
Features	Description
WLAN Standard	IEEE 802.11b/g/n CSMA/CA
Frequency Range	2.4~2.484GHz (2.4GHz ISM Band)
Channels	Ch1~Ch11(For 20MHz Channels)
Modulation	802.11b (DSSS): DBPSK, DQPSK, CCK; 802.11g (OFDM): BPSK, QPSK, 16QAM, 64QAM; 802.11n (OFDM): BPSK, QPSK, 16QAM, 64QAM;
Data Rate	802.11b: 1, 2, 5.5, 11Mbps; 802.11g: 6, 9, 12, 18, 24, 36, 48, 54Mbps; 802.11n (HT20): MCS0~MCS7(1T1R_SISO) 6.5~72.2Mbps; 802.11n (HT40): MCS0~MCS7(1T1R_SISO) 13.5~150Mbps;
Frequency Tolerance	$\leq \pm 20\text{ppm}$

2.4G Transmitter Specifications

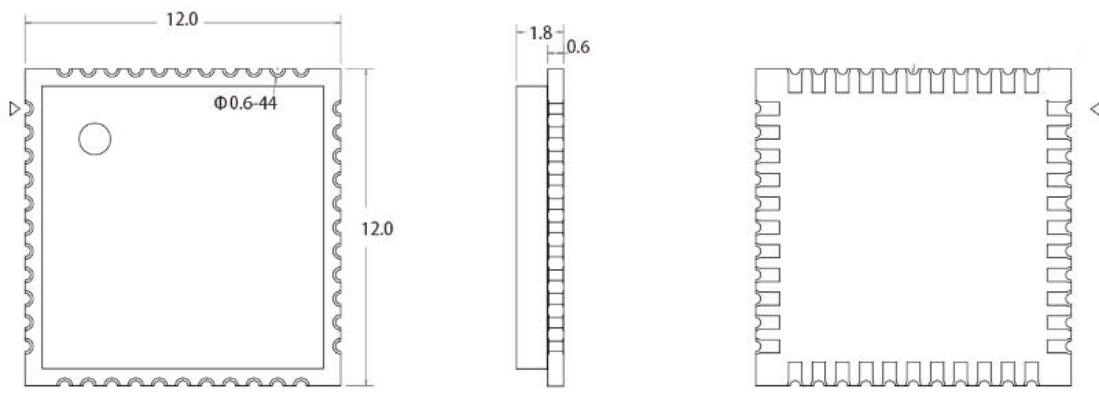
TX Rate	TX Power (dBm)	TX Power Tolerance (dBm)	EVM (dB)
802.11b@1Mbps	Recommended Target TX Power =19	± 2	$\leq -10\text{dB}$
802.11b@11Mbps	Calibrated TX Power =17	± 2	$\leq -10\text{dB}$
802.11g@6Mbps	Recommended Target TX Power ≤ 16	± 2	$\leq -10\text{dB}$
802.11g@54Mbps	Calibrated TX Power =14	± 2	$\leq -25\text{dB}$
802.11n@HT20_MCS0	Recommended Target TX Power ≤ 16	± 2	$\leq -10\text{dB}$
802.11n@HT20_MCS7	Calibrated TX Power =14	± 2	$\leq -28\text{dB}$
802.11n@HT40_MCS0	Recommended Target TX Power ≤ 16	± 2	$\leq -10\text{dB}$
802.11n@HT40_MCS7	Calibrated TX Power =14	± 2	$\leq -28\text{dB}$

2.4G Receiver Specifications

RX Rate	Min Input Level(dBm)	Max Input Level(dBm)	PER
802.11b@1Mbps	-92	-10	< 8%
802.11b@11Mbps	-86	-10	< 8%
802.11g@6Mbps	-90	-15	< 10%
802.11g@54Mbps	-72	-15	< 10%
802.11n@HT20_MCS0	-88	-15	< 10%
802.11n@HT20_MCS7	-67	-15	< 10%
802.11n@HT40_MCS0	-86	-15	< 10%
802.11n@HT40_MCS7	-66	-15	< 10%

5. Mechanical Specifications

5.1 Module Outline Drawing

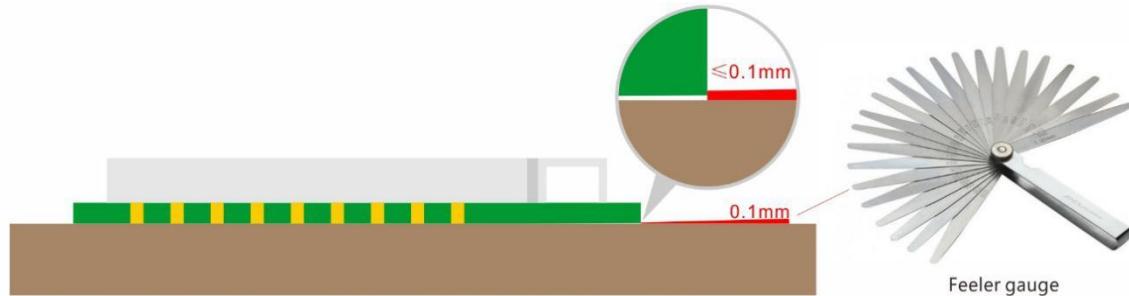


(Top view)

(Side view)

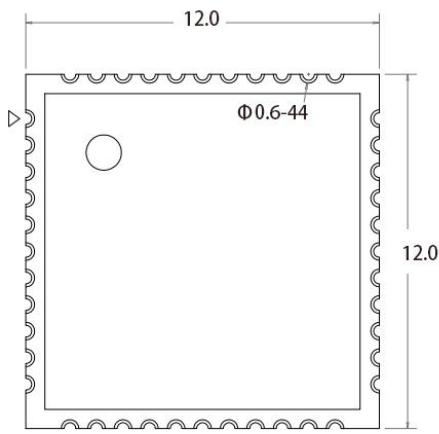
(Bottom view)

Module dimension: 12.0*12.0*1.8mm (L*W*H; Tolerance: $\pm 0.3\text{mm}_L/W$, $\pm 0.2\text{mm}_H$)

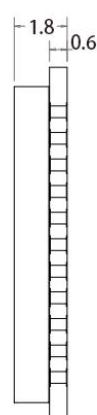


Module Bow and Twist: $\leq 0.1\text{mm}$

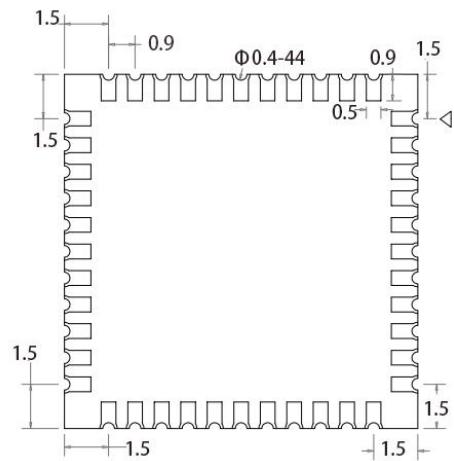
5.2 Mechanical Dimensions



(Top view)



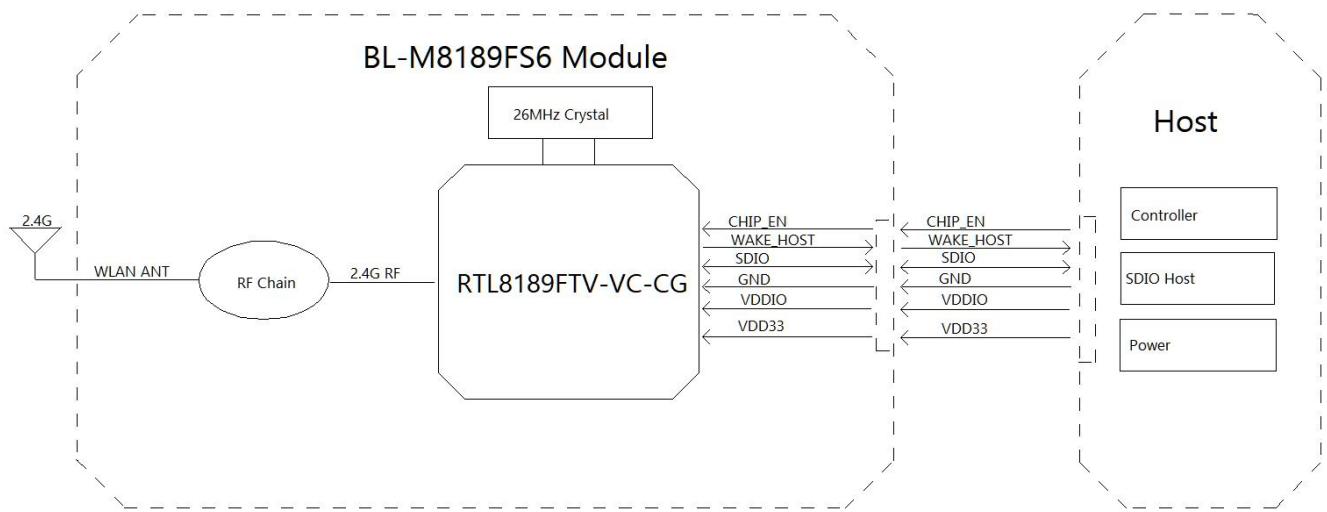
(Side view)



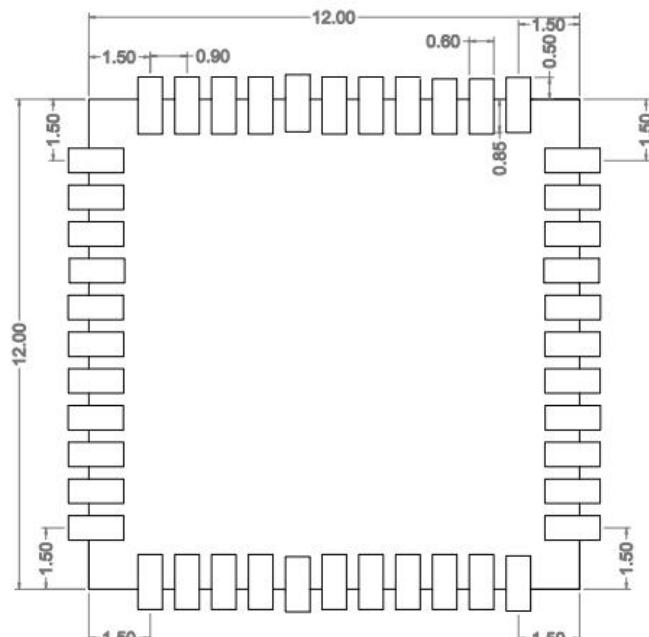
(Bottom view)

6. Application Information

6.1 Typical Application Circuit

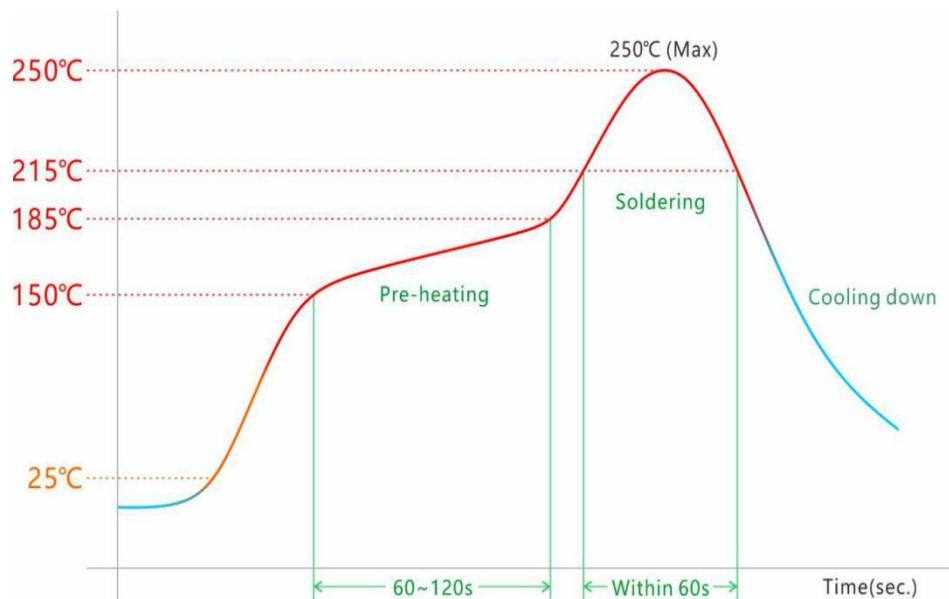


6.2 Recommend PCB Layout Footprint



Design size mm

6.3 Reflow Soldering Standard Conditions



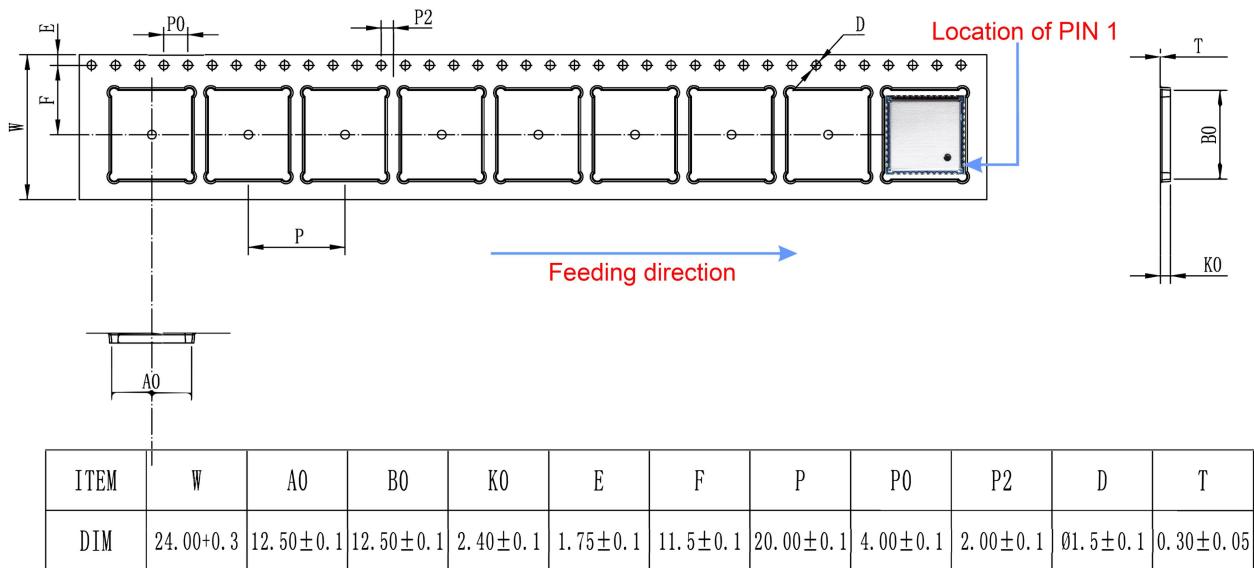
Please use the reflow within 2 times.
Set up the highest temperature within 250°C.

7. Key Components Of Module

No.	Parts	Specification	Manufacturer	Note
1	Chipset	RTL8189FTV-VC-CG	Realtek Semiconductor Corp.	
2	PCB	BL-M8189FS6	ShenZhen Tie Fa Technology Limited	
			SHEN ZHEN QILI ELECTRON CO.,LTD	
			Quzhou Sunlord Electronics Co.,Ltd	
			Huizhou Dayawan Kexiang Technology Circuit Board Co., Ltd	
3	Crystal	26MHz-3225	LUCKI CM ELECTRONICS CO., LTD	
			HUBEI TKD CRYSTAL ELECTRONIC SCIENCE AND TECHNOLOGY CO.,LTD	
			JinHua East Crystal Electronic Co.,Ltd.	
			Chengde oscillator Electronic Technology Co.,Ltd	

8. Package and Storage Information

8.1 Package Dimensions



Package specification:

1. 1000 modules per roll and 5,000 modules per box.
2. Outer box size: 37.5*36*29cm.
3. The diameter of the blue environment-friendly rubber plate is 13 inches, with a total thickness of 28mm (with a width of 24mm carrying belt).
4. Put 1 package of dry agent (20g) and humidity card in each anti-static vacuum bag.
5. Each carton is packed with 5 boxes.

8.2 Storage Conditions

Absolute Maximum Ratings:

Storage temperature: -40°C to +85°C

Storage humidity: 10% to 95% RH (Non-Condensing)

Recommended Storage Conditions:

Storage temperature: 5°C to +40°C

Storage humidity: 20% to 90% RH

Please use this Module within 12month after vacuum-packaged.

The Module shall be stored without opening the packing.

After the packing opened, the Module shall be used within 72hours.

When the color of the humidity indicator in the packing changed,
the Module shall be baked before soldering.

Baking condition: 60°C, 24hours, 1time.



ESD Sensitivity:

ESD Protection: 2KV(HBM, Maximum rating)

The Module is a static-sensitive electronic device.

Do not operate or store near strong electrostatic fields.

Take proper ESD precautions!

ESD CAUTION

FCC Statement

This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

Reorient or relocate the receiving antenna.

Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.

Consult the dealer or an experienced radio/TV technician for help important announcement

Radiation Exposure Statement

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator and your body.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter. Country Code selection feature to be disabled for products marketed to the US/Canada.

This device is intended only for OEM integrators under the following conditions:

1. The antenna must be installed such that 20 cm is maintained between the antenna and users, and
2. The transmitter module may not be co-located with any other transmitter or antenna,
3. For all products market in US, OEM has to limit the operation channels in CH1 to CH11 for 2.4G band by supplied firmware programming tool. OEM shall not supply any tool or info to the end-user regarding to Regulatory Domain change. (if modular only test Channel 1-11)

As long as the three conditions above are met, further transmitter testing will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Important Note:

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

End Product Labeling

The final end product must be labeled in a visible area with the following"

Contains FCC ID: 2AL6KBLM8189FS6"

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as shown in this manual.

Integration instructions for host product manufacturers according to KDB 996369 D03 OEM Manual v01r01

2.2 List of applicable FCC rules

CFR 47 FCC PART 15 SUBPART C has been investigated. It is applicable to the modular transmitter

2.3 Specific operational use conditions

This module is stand-alone modular. If the end product will involve the Multiple simultaneously transmitting condition or different operational conditions for a stand-alone modular transmitter in a host, host manufacturer have to consult with module manufacturer for the installation method in end system.

2.4 Limited module procedures

Not applicable

2.5 Trace antenna designs

Not applicable

2.6 RF exposure considerations

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

2.7 Antennas

This radio transmitter **FCC ID:2AL6KBLM8189FS6** has been approved by Federal Communications Commission to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Antenna No.	Model No. of antenna:	Type of antenna:	Gain of the antenna (Max.)		Frequency range:
			Antenna 1	Antenna 2	
2.4G Wi-Fi	/	External Antenna	2.45	N/A	2412-2462MHz

2.8 Label and compliance information

The final end product must be labeled in a visible area with the following" Contains **FCC ID:2AL6KBLM8189FS6**".

2.9 Information on test modes and additional testing requirements

Host manufacturer is strongly recommended to confirm compliance with FCC requirements for the transmitter when the module is installed in the host.

2.10 Additional testing, Part 15 Subpart B disclaimer

Host manufacturer is responsible for compliance of the host system with module installed with all other applicable requirements for the system such as Part 15 B.

2.11 Note EMI Considerations

Host manufacture is recommended to use D04 Module Integration Guide recommending as "best practice" RF design engineering testing and evaluation in case non-linear interactions generate additional non-compliant limits due to module placement to host components or properties.

2.12 How to make changes

This module is stand-alone modular. If the end product will involve the Multiple simultaneously transmitting condition or different operational conditions for a stand-alone modular transmitter in a host, host manufacturer have to consult with module manufacturer for the installation method in end system. According to the KDB 996369 D02 Q&A Q12, that a host manufacture only needs to do an evaluation (i.e., no C2PC required when no emission exceeds the limit of any individual device (including unintentional radiators) as a composite. The host manufacturer must fix any failure.